# Low-Voltage 16-Bit Buffer with Bus Hold 1.8/2.5/3.3 V

(3-State, Non-Inverting)

The 74ALVCH16244 is an advanced performance, non-inverting 16-bit buffer. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems.

The 74ALVCH16244 is nibble controlled with each nibble functioning identically, but independently. The control pins may be tied together to obtain full 16-bit operation. The 3-state outputs are controlled by an Output Enable (OEn) input for each nibble. When OEn is LOW, the outputs are on. When OEn is HIGH, the outputs are in the high impedance state. The data inputs include active bushold circuitry, eliminating the need for external pull-up resistors to hold unused or floating inputs at a valid logic state.

• Designed for Low Voltage Operation:  $V_{CC} = 1.65 - 3.6 \text{ V}$ 

• 3.6 V Tolerant Inputs and Outputs

• High Speed Operation: 2.5 ns max for 3.0 to 3.6 V

3.0 ns max for 2.3 to 2.7 V 6.0 ns max for 1.65 to 1.95 V

• Static Drive: ±24 mA Drive at 3.0 V

±18 mA Drive at 2.3 V ±6 mA Drive at 1.65 V

- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- IOFF Specification Guarantees High Impedance When  $V_{CC} = 0 \text{ V}^{\dagger}$
- Near Zero Static Supply Current in All Three Logic States (20 μA)
   Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±250 mA @ 125°C
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- Second Source to Industry Standard 74ALVCH16244

†To ensure the outputs activate in the 3–state condition, the output enable pins should be connected to  $V_{CC}$  through a pull–up resistor. The value of the resistor is determined by the current sinking capability of the output connected to the  $\overline{OE}$  pin.



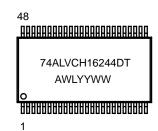
# ON Semiconductor™

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#### **MARKING DIAGRAM**



TSSOP-48 DT SUFFIX CASE 1201



= Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

# ORDERING INFORMATION

Device	Package	Shipping
74ALVCH16244DT	TSSOP	39 Units/Rail
74ALVCH16244DTR	TSSOP	2500/Tape & Reel

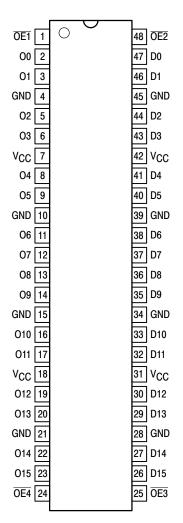


Figure 1. 48–Lead Pinout (Top View)

# PIN NAMES

Pins	Function
OEn	Output Enable Inputs
D0-D15	Inputs
O0-O15	Outputs

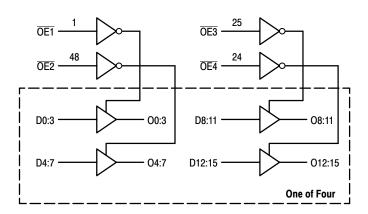


Figure 2. Logic Diagram

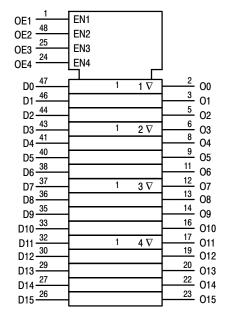


Figure 3. IEC Logic Diagram

OE1	D0:3	O0:3	OE2	D4:7	O4:7	OE3	D8:11	O8:11	OE4	D12:15	O12:15
L	L	L	L	L	L	L	L	L	L	L	L
L	Н	Н	L	Н	Н	L	Н	Н	L	Н	Н
Н	Х	Z	Н	Х	Z	Н	Х	Z	Н	Х	Z

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for ICC reasons, DO NOT FLOAT Inputs

# MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage	-0.5 to +4.6	V
VI	DC Input Voltage	-0.5 to +4.6	V
VO	DC Output Voltage	-0.5 to +4.6	V
lıĸ	DC Input Diode Current V <sub>I</sub> < GND	-50	mA
lok	DC Output Diode Current V <sub>O</sub> < GND	-50	mA
IO	DC Output Sink Current	±50	mA
ICC	DC Supply Current per Supply Pin	±100	mA
IGND	DC Ground Current per Ground Pin	±100	mA
TSTG	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
θJA	Thermal Resistance (Note 2)	90	°C/W
MSL	Moisture Sensitivity	Level 1	
FR	Flammability Rating Oxygen Index: 30% – 35%	UL-94-VO (0.125 in)	
VESD	ESD Withstand Voltage  Human Body Model (Note 3)  Machine Model (Note 4)  Charged Device Model (Note 5)	> 200	V
LATCH-UP	Latch–Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 6)	±250	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. IO absolute maximum rating must be observed.
- 2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to EIA/JESD22-A115-A.
- 5. Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
VCC	Supply Voltage	2.3 1.5	3.6 3.6	V	
VI	Input Voltage	0	3.6	V	
VO	Output Voltage	0	3.6	V	
TA	Operating Free–Air Temperature		-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

7. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

# DC ELECTRICAL CHARACTERISTICS

			$T_A = -40^\circ$	C to +85°C	
Symbol	Parameter	Condition	Min	Max	Unit
VIH	HIGH Level Input Voltage	$1.65 \text{ V} \leq \text{V}_{CC} < 2.3 \text{ V}$	0.65 × V <sub>CC</sub>		V
	(Note 8)	$2.3 \text{ V} \leq \text{V}_{CC} \leq 2.7 \text{ V}$	1.7		
		$2.7 \text{ V} < \text{V}_{CC} \le 3.6 \text{ V}$	2.0		
$V_{IL}$	LOW Level Input Voltage	$1.65 \text{ V} \leq \text{V}_{CC} < 2.3 \text{ V}$		$0.35 \times V_{CC}$	V
	(Note 8)	$2.3 \text{ V} \leq \text{V}_{CC} \leq 2.7 \text{ V}$		0.7	
		$2.7 \text{ V} < \text{V}_{CC} \le 3.6 \text{ V}$		0.8	
VOH	HIGH Level Output Voltage	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; I_{OH} = -100 \mu\text{A}$	V <sub>CC</sub> - 0.2		V
		V <sub>CC</sub> = 1.65 V; I <sub>OH</sub> = -4 mA	1.20		
		$V_{CC} = 2.3 \text{ V; } I_{OH} = -6 \text{ mA}$	2.0		
		V <sub>CC</sub> = 2.3 V; I <sub>OH</sub> = -12 mA	1.7		
		$V_{CC} = 2.7 \text{ V; } I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V; } I_{OH} = -12 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V; } I_{OH} = -24 \text{ mA}$	2.0		
VOL	LOW Level Output Voltage	$1.65 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}; I_{OL} = 100 \mu\text{A}$		0.2	V
		V <sub>CC</sub> = 1.65 V; I <sub>OL</sub> = 4 mA		0.45	
		V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 6 mA		0.4	
		V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 12 mA		0.7	
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55	
VOL	LOW Level Output Voltage	$V_{CC} = 3.6 \text{ V}; V_I = 0 \text{ to } 3.6 \text{ V}$		±500	μΑ
Ц	Input Leakage Current	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 3.6 \text{ V}$		±5.0	μΑ
I <sub>I</sub> (HOLD)	Minimum Bus-hold Input	V <sub>CC</sub> = 3.0 V, V <sub>IN</sub> = 0.8 V	75		μΑ
	Current	V <sub>CC</sub> = 3.0 V, V <sub>IN</sub> = 2.0 V	-75		
		$V_{CC} = 2.3 \text{ V}, V_{IN} = 0.7 \text{ V}$	45		
		V <sub>CC</sub> = 2.3 V, V <sub>IN</sub> = 1.7 V	- 45		
		V <sub>CC</sub> = 1.65 V, V <sub>IN</sub> = 0.58 V	25		
		V <sub>CC</sub> = 1.65 V, V <sub>IN</sub> = 1.07 V	-25		
loz	3-State Output Current	$1.65~\text{V} \leq \text{V}_{CC} \leq 3.6~\text{V}; 0~\text{V} \leq \text{V}_{O} \leq 3.6~\text{V}; \text{V}_{I} = \text{V}_{IH}~\text{or}~\text{V}_{IL}$		±10	μΑ
loff	Power–Off Leakage Current	V <sub>CC</sub> = 0 V; V <sub>I</sub> or V <sub>O</sub> = 3.6 V		10	μΑ
ICC	Quiescent Supply Current	$1.65 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}; \text{ V}_{I} = \text{GND or V}_{CC}$		40	μΑ
	(Note 9)	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 3.6 \text{ V} \le \text{V}_{I}, \text{V}_{O} \le 3.6 \text{ V}$		±40	
ΔlCC	Increase in ICC per Input	$2.7 \text{ V} < \text{V}_{CC} \le 3.6 \text{ V}; \text{V}_{IH} = \text{V}_{CC} - 0.6 \text{ V}$		750	μΑ

<sup>8.</sup> These values of V<sub>I</sub> are used to test DC electrical characteristics only.
9. Outputs disabled or 3–state only.

AC CHARACTERISTICS (Note 10;  $t_R = t_F = 2.0 \text{ ns}$ ;  $C_L = 30 \text{ pF}$ ;  $R_L = 500 \Omega$ )

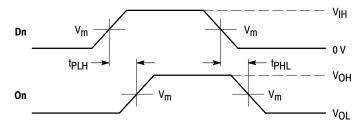
				Limits						
					T <sub>A</sub> = -40°	C to +85°C				
			V <sub>CC</sub> = 3.0	V to 3.6 V	V <sub>CC</sub> = 2.3	V to 2.7 V	V <sub>CC</sub> = 1.65	5 V – 1.95 V		
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit	
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation Delay Input to Output	1	0.5 0.5	2.5 2.5	0.5 0.5	3.0 3.0	0.5 0.5	6.0 6.0	ns	
<sup>t</sup> PZH <sup>t</sup> PZL	Output Enable Time to High and Low Level	2	0.5 0.5	3.5 3.5	0.5 0.5	4.1 4.1	0.5 0.5	8.2 8.2	ns	
<sup>t</sup> PHZ <sup>t</sup> PLZ	Output Disable Time From High and Low Level	2	0.5 0.5	3.5 3.5	0.5 0.5	3.8 3.8	0.5 0.5	6.8 6.8	ns	
toshl toslh	Output-to-Output Skew (Note 11)			0.5 0.5		0.5 0.5		0.75 0.75	ns	

<sup>10.</sup> For  $C_L = 50$  pF, add approximately 300 ps to the AC maximum specification.

# **CAPACITIVE CHARACTERISTICS**

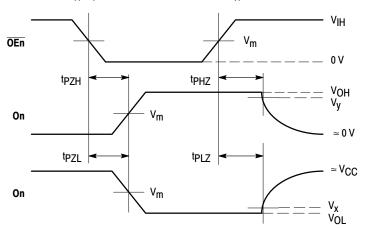
Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	Note 12	6	рF
C <sub>OUT</sub>	Output Capacitance	Note 12	7	рF
C <sub>PD</sub>	Power Dissipation Capacitance	Note 12, 10 MHz	20	pF

 $12.V_{CC} = 1.8$ , 2.5 or 3.3 V;  $V_{I} = 0.4$  V or  $V_{CC}$ .



# WAVEFORM 1 - PROPAGATION DELAYS

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 



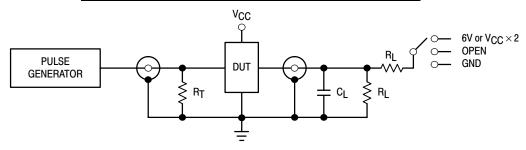
# WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

 $t_{\mbox{\scriptsize R}}$  =  $t_{\mbox{\scriptsize F}}$  = 2.0 ns, 10% to 90%; f = 1 MHz;  $t_{\mbox{\scriptsize W}}$  = 500 ns

Figure 4. AC Waveforms

<sup>11.</sup> Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

		Vcc							
Symbol	3.3 V ±0.3 V	2.5 V ±0.2 V	1.8 V ±0.15 V						
V <sub>IH</sub>	2.7 V	Vcc	Vcc						
V <sub>m</sub>	1.5 V	V <sub>CC</sub> /2	V <sub>CC</sub> /2						
V <sub>X</sub>	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.15 V	V <sub>OL</sub> + 0.15 V						
Vy	V <sub>OH</sub> – 0.3 V	V <sub>OH</sub> – 0.15 V	V <sub>OH</sub> – 0.15 V						



TEST	SWITCH
t <sub>PLH</sub> , t <sub>PHL</sub>	Open
tPZL, tPLZ	6 V at $V_{CC}$ = 3.3 ±0.3 V; $V_{CC} \times$ 2 at $V_{CC}$ = 2.5 ±0.2 V; 1.8 ±0.15 V
tPZH, tPHZ	GND

 $C_L$  = 50 pF for V<sub>CC</sub> = 3.0 ± 0.3 V  $R_L$  = 500  $\Omega$  or equivalent  $R_T$  = Z<sub>OUT</sub> of pulse generator (typically 50  $\Omega$ )

Figure 5. Test Circuit

# AC CHARACTERISTICS ( $t_R = t_F = 2.0 \text{ ns}$ ; $C_L = 50 \text{ pF}$ ; $R_L = 500 \Omega$ )

				Lim	nits		
				T <sub>A</sub> = -40°C	c to +85°C		
			V <sub>CC</sub> = 3.0	V to 3.6 V	V <sub>CC</sub> =	2.7 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
tPLH tPHL	Propagation Delay Input to Output	3	1.0 1.0	3.0 3.0		3.6 3.6	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Output Enable Time to High and Low Level	4	1.0 1.0	4.4 4.4		5.4 5.4	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Output Disable Time From High and Low Level	4	1.0 1.0	4.1 4.1		4.6 4.6	ns
tOSHL tOSLH	Output-to-Output Skew (Note 13)			0.5 0.5		0.5 0.5	ns

<sup>13.</sup> Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

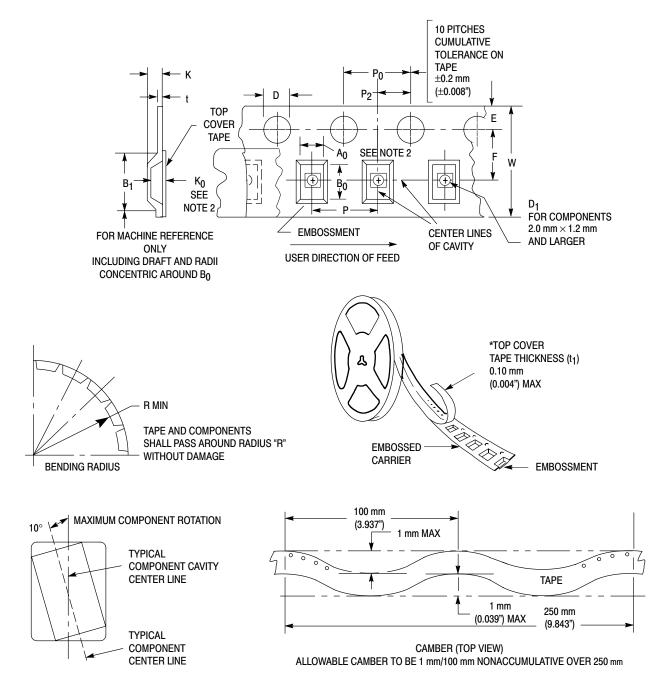


Figure 6. Carrier Tape Specifications

#### **EMBOSSED CARRIER DIMENSIONS** (See Notes 14 and 15)

Tape Size	B <sub>1</sub> Max	D	D <sub>1</sub>	E	F	к	Р	P <sub>0</sub>	P <sub>2</sub>	R	Т	w
24mm	20.1mm (0.791")	1.5 + 0.1mm -0.0 (0.059 +0.004" -0.0)	1.5mm Min (0.060")	1.75 ±0.1 mm (0.069 ±0.004")	11.5 ±0.10 mm (0.453 ±0.004")	11.9 mm Max (0.468")	16.0 ±0.1 mm (0.63 ±0.004")	4.0 ±0.1 mm (0.157 ±0.004")	2.0 ±0.1 mm (0.079 ±0.004")	30 mm (1.18")	0.6 mm (0.024")	24.3 mm (0.957")

<sup>14.</sup> Metric Dimensions Govern-English are in parentheses for reference only.

<sup>15.</sup> A<sub>0</sub>, B<sub>0</sub>, and K<sub>0</sub> are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity.

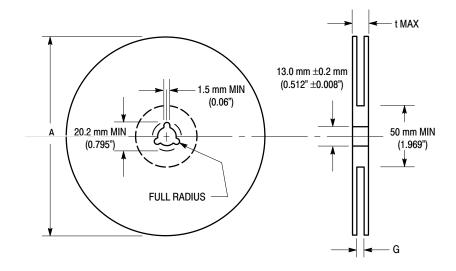


Figure 7. Reel Dimensions

# **REEL DIMENSIONS**

Tape Size	A Max	G	t Max
24 mm	360 mm	24.4 mm + 2.0 mm, -0.0	30.4 mm
	(14.173")	(0.961" + 0.078", -0.00)	(1.197")

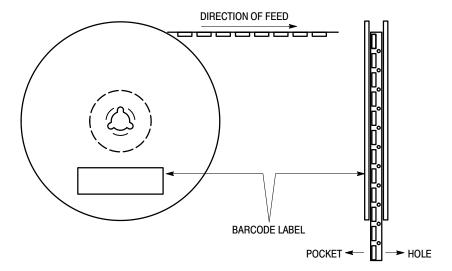


Figure 8. Reel Winding Direction

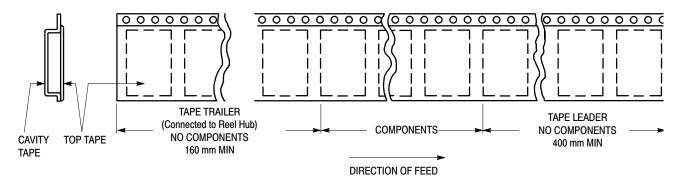


Figure 9. Tape Ends for Finished Goods

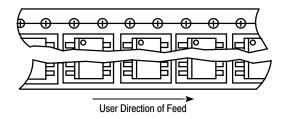


Figure 10. Reel Configuration

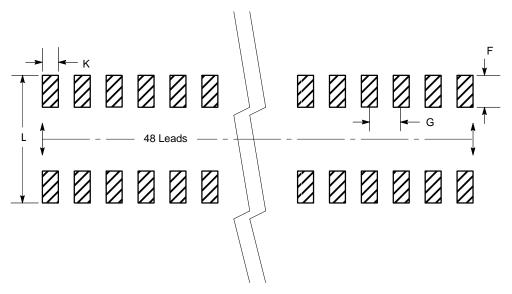
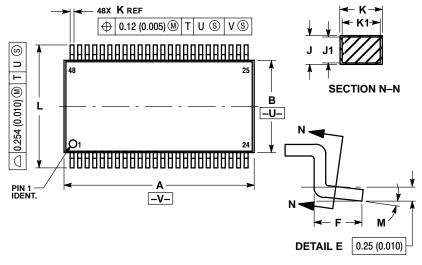


Figure 11. Package Footprint

#### **PACKAGE DIMENSIONS**

# **TSSOP DT SUFFIX** CASE 1201-01

**ISSUE A** 

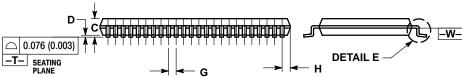


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  5. TERMINAL NUMBERS ARE SHOWN FOR
- MAI EHIAL CONDITION.

  5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

  6. DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	12.40	12.60	0.488	0.496
В	6.00	6.20	0.236	0.244
C		1.10		0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.50 BSC		0.0197 BSC	
Н	0.37		0.015	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.17	0.27	0.007	0.011
K1	0.17	0.23	0.007	0.009
L	7.95	8.25	0.313	0.325
М	0 °	8 °	0 °	8 °





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